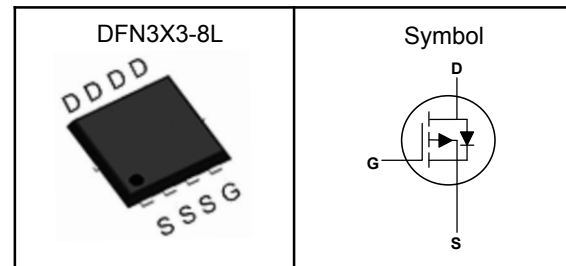


P-Channel Enhancement Mode MOSFET
Features

- Low $R_{ds(on)}$ for low conduction loss
- Reliable and Rugged
- ROHS Compliant & Halogen-Free

Applications

- Power Management in Desktop Computer
- DC/DC Converters

Pin Description


V_{bss}	-30	V
$R_{ds(ON)-Typ}$	15	m Ω
I_D	-32	A

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	P-Channel	Unit
V_{bss}	Drain-Source Voltage	-30	V
V_{GSS}	Gate-Source Voltage	± 25	V
T_J	Maximum Junction Temperature	-55 to 150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$I_{DM}^{①}$	Pulse Drain Current Tested	-70	A
I_D	Continuous Drain Current	$T_C=25^\circ\text{C}$ -32	A
I_D	Continuous Drain Current	$T_A=25^\circ\text{C}$ -10.5	A
P_D	Maximum Power Dissipation	$T_C=25^\circ\text{C}$ 29.8	W
P_D	Maximum Power Dissipation	$T_A=25^\circ\text{C}$ 3.1	W
I_{AS}	Avalanche Current	$L=0.5\text{mH}$ 14	A
E_{AS}	Avalanche Energy, Single pulse	$L=0.5\text{mH}$ 49	mJ

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}^{③}$	Thermal Resistance-Junction to Ambient	75	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case	4.2	$^\circ\text{C/W}$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C .

Note ③ : Surface Mounted on 1in^2 FR-4 board with 1oz.



P-Channel Enhancement Mode MOSFET

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-30	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-24V, V_{GS}=0V$	---	---	-1	μA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.3	---	-2.5	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 25V, V_{DS}=0V$	---	---	± 10	μA
$R_{DS(on)}$	Drain-Source On-state Resistance	$V_{GS}=-10V, I_D=-16A$	---	15	19	$m\Omega$
		$V_{GS}=-5V, I_D=-8A$	---	24	32	$m\Omega$
Dynamic Characteristics^⑤						
C_{iss}	Input Capacitance	$V_{GS}=0V, V_{DS}=-15V, \text{Freq.}=1\text{MHz}$	---	1000	---	pF
C_{oss}	Output Capacitance		---	220	---	
C_{rss}	Reverse Transfer Capacitance		---	170	---	
$T_{d(on)}$	Turn-on Delay Time	$V_{DD}=-15V, R_L=15\Omega, I_{DS}=-1A, V_{GEN}=-10V, R_G=6\Omega$	---	11.2	---	nS
T_r	Turn-on Rise Time		---	10.6	---	
$T_{d(off)}$	Turn-off Delay Time		---	37	---	
T_f	Turn-off Fall Time		---	50	---	
Q_g	Total Gate Charge	$V_{DS}=-15V, V_{GS}=-10V, I_D=-16A$	---	20	---	nC
Q_{gs}	Gate-Source Charge		---	1.1	---	
Q_{gd}	Gate-Drain Charge		---	7.7	---	
Source-Drain Characteristics						
$V_{SD}^{④}$	Diode Forward Voltage	$V_{GS}=0V, I_S=-1A, T_J=25^{\circ}\text{C}$	---	-0.7	-1.0	V
t_{rr}	Reverse Recovery Time	$I_F=-16A, di/dt=100A/\mu s, T_J=25^{\circ}\text{C}$	---	18	---	nS
Q_{rr}	Reverse Recovery Charge		---	9	---	nC

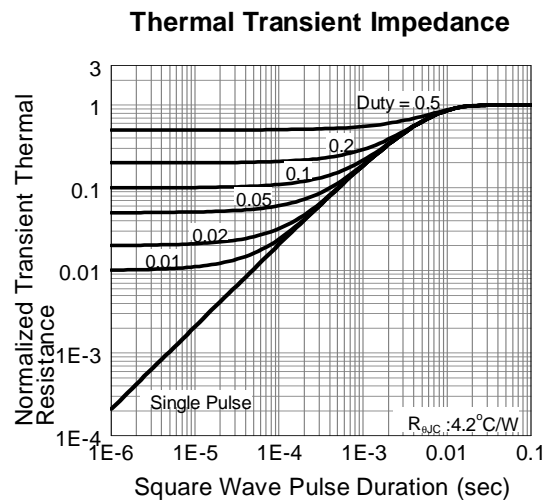
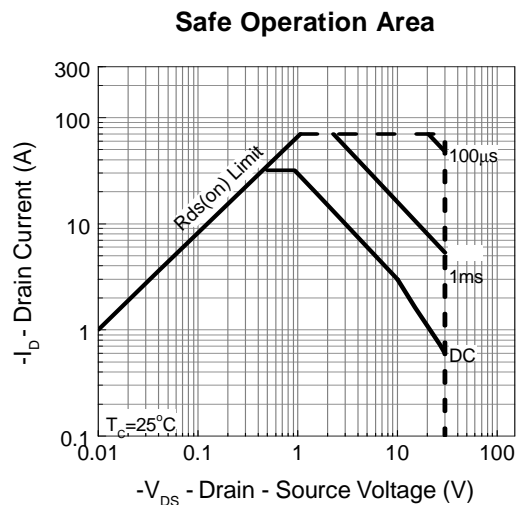
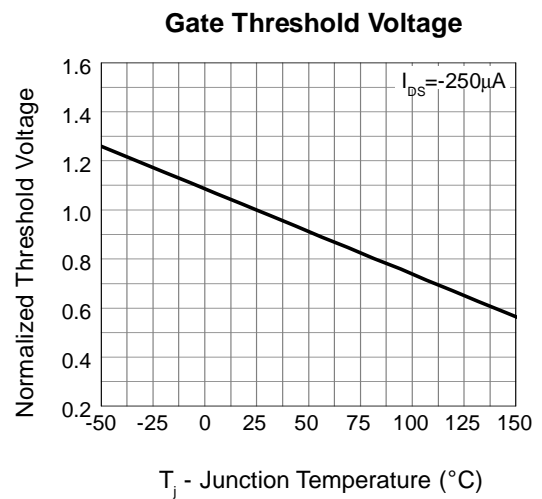
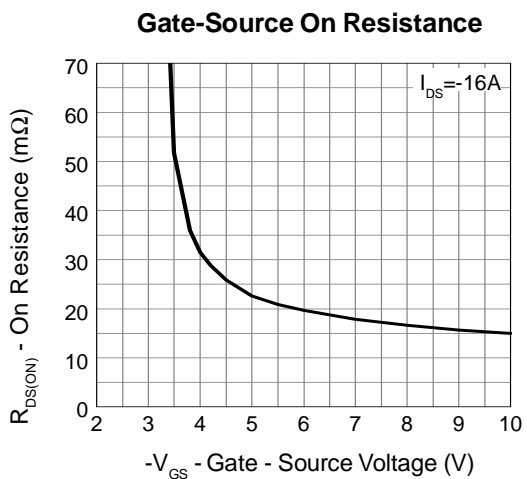
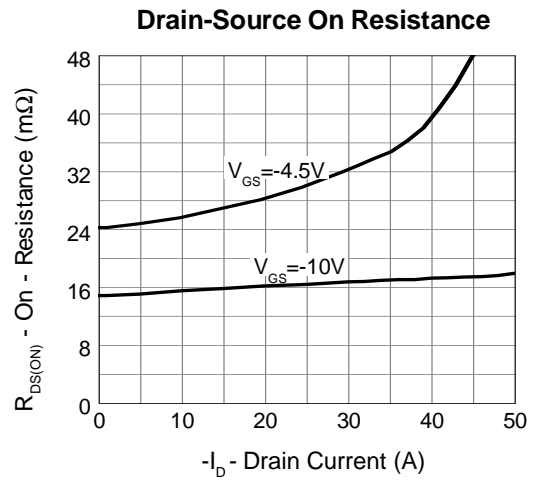
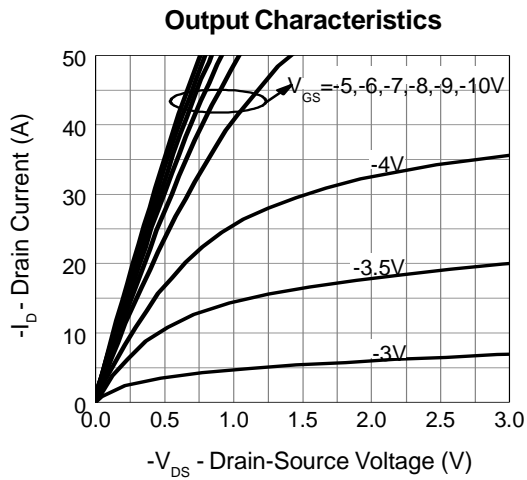
Note ④: Pulse test (pulse width 300us, duty cycle 2%).

Note ⑤: Guaranteed by design, not subject to production testing.



P-Channel Enhancement Mode MOSFET

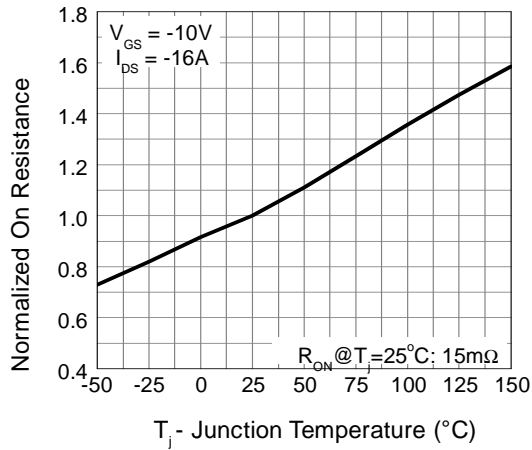
Typical Characteristics



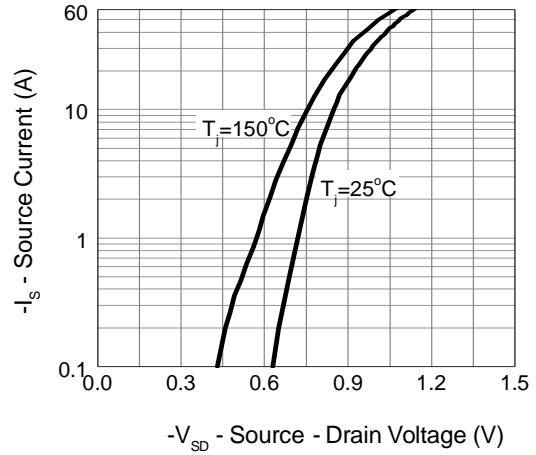


P-Channel Enhancement Mode MOSFET

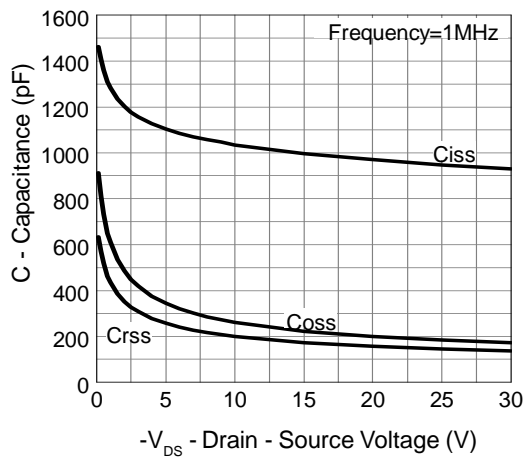
Drain-Source On Resistance



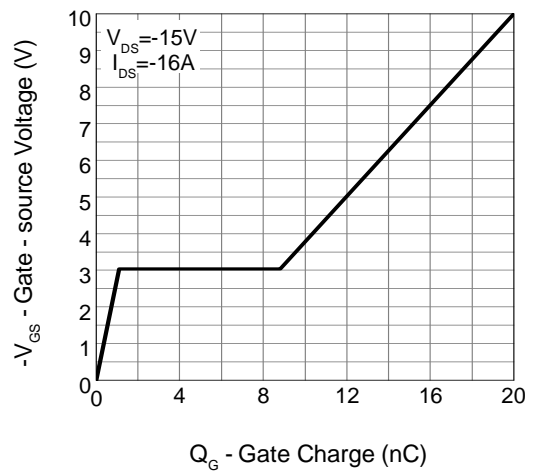
Source-Drain Diode Forward



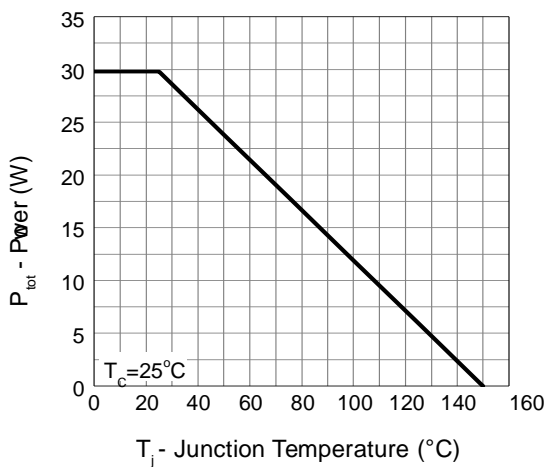
Capacitance



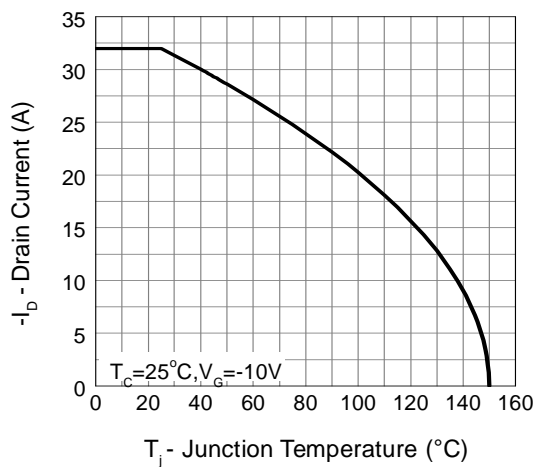
Gate Charge

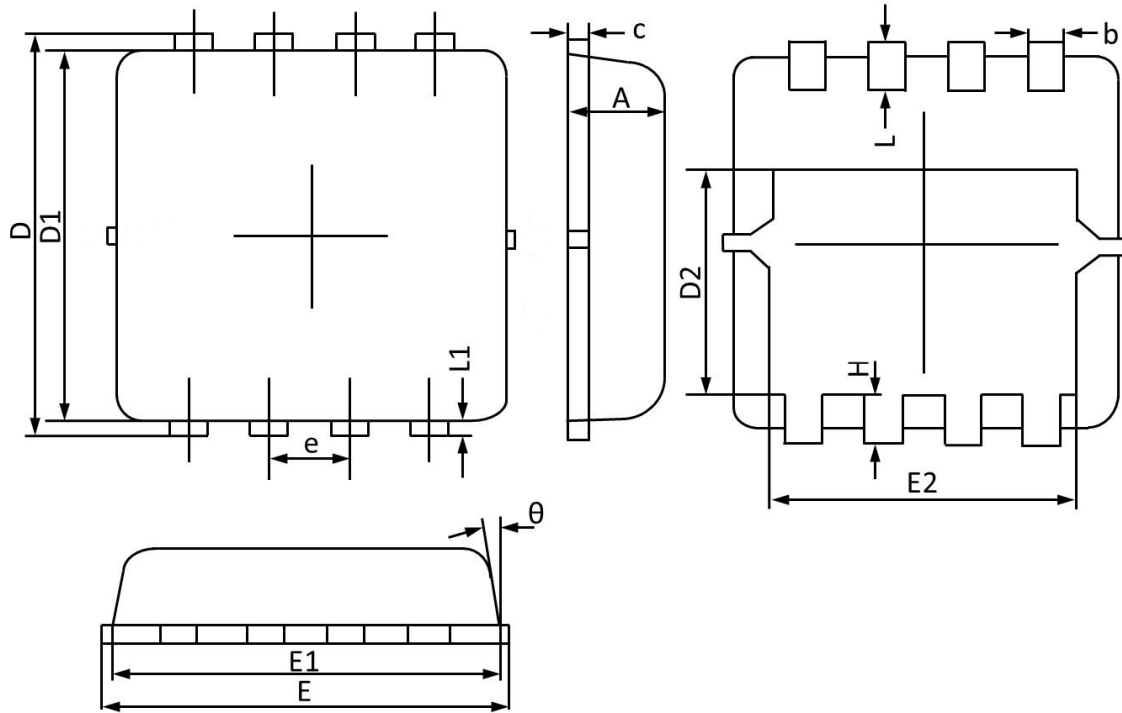


Power Dissipation



Drain Current



P-Channel Enhancement Mode MOSFET
DFN3X3-8L Package Outline Dimensions


Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	0.70	0.75	0.85	E1	2.90	3.10	3.25
b	0.24	0.30	0.35	E2	2.35	2.50	2.60
c	0.10	0.17	0.25	e	0.65 BSC		
D	3.10	3.30	3.45	H	0.30	0.40	0.50
D1	2.90	3.05	3.20	L	0.30	0.40	0.50
D2	1.45	1.70	1.95	L1	--	0.13	--
E	3.05	3.25	3.40	theta	0°		14°